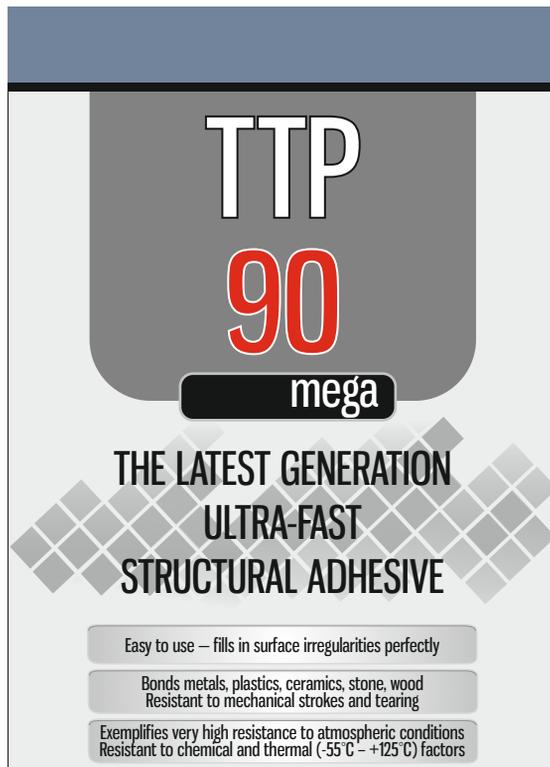



MEGA TTP90
TTP90


**TTP
90**
mega

**THE LATEST GENERATION
ULTRA-FAST
STRUCTURAL ADHESIVE**

- Easy to use – fills in surface irregularities perfectly
- Bonds metals, plastics, ceramics, stone, wood
Resistant to mechanical strokes and tearing
- Exemplifies very high resistance to atmospheric conditions
Resistant to chemical and thermal (-55°C – +125°C) factors

CAUTION

All information, including illustrations, are reliable. However, the users should evaluate the usability of each product for a given application. TTP Polska Sp. z o.o. does not guarantee the accuracy of all information and does not accept responsibility for how the products are used. The liabilities of TTP Polska Sp. z o.o. are limited solely to the standard terms and conditions of sale of the product and in no case whatsoever does TTP Polska Sp. z o.o. bear any responsibility for accidental or indirect damages resulting in the sale, use and improper use of the product.

GENERAL INFORMATION

MEGA TTP-90 is the latest generation ultra-fast adhesive based on methacrylate, of high viscosity, cured at low temperatures and in thick layers. Strong adhesion properties and high viscosity of the adhesive also allow adhesive bonding on vertical surfaces. **MEGA TTP-90** features perfect adhesion to thermohardened composites (SMC, BMC, RTM), fibre glass composites (CFRP), thermoplastic plastics, metals, (including non-ferrous and coated metals). Additionally, it may be used for the adhesive bonding of wood, concrete and many other materials and their combinations. Adhesive bonding established with the use of **MEGA TTP-90** is characterised by high resistance to: vibrations, mechanical strokes, UV radiation, water, salt solutions, acids, lyes, etc. **MEGA TTP-90** in installations caters for maximum equilibrium between mechanical force and resistance to influences, and at the same time it is easy and fast to use.

TECHNICAL DATA

Colour: black
 Mixing ratio: 1:1
 Curing system: exothermal
 Density at 20°C: 1,03 g/cm³
 Viscosity at 20°C: 5,000 cPs
 Preparation time: 1 min.
 Formation time at 20°C: ca. 0.5 min.
 Touch-dry time at 20°C: 1 min.
 Bonding time to mechanical resistance at 20°C: 4–5 min.
 Bonding time to full chemical resistance at 20°C: 12 h
 Thermal resistance: -55°C – 125°C
 Fissure filling: 2 mm
 Shearing resistance acc. to ASTM D1002 in N/mm²: up to 25
 Tensile strength acc. to ASTM D638 in N/mm²: up to 25
 Dielectric strength acc. to ASTM D149 in kV/mm: 20
 Safety measures: provided in the safety data sheet.

USAGE

Apply directly onto one of the bonded surfaces. In order to secure maximum bonding strength, the surfaces must be covered within a specified preparation time. All activities during adhesive bonding, positioning and fixing should be carried out within the preparation time. Movement of the bonded parts of the surfaces after the fixation time may cause the established bond to be less secure than usual. The right bond is guaranteed, when the adhesive is used at 18–26°C. Temperatures below 18°C slow down the process of adhesion, and above 26°C increase the curing speed.

MEGA TTP-90 jest available in a double cartridge. In order to apply the adhesive correctly, a mixing tip and gun applicator should be used. A gun applicator facilitates the right application of adhesive onto the bonded surfaces.

Note: if the adhesive is applied with pauses lasting more than 2 minutes, the mixing tip should be replaced.

CLASSIFICATION

Article code	Name	Packaging	Type
TTP90	MEGA TTP-90	50 ml — 2 x 25 ml	adhesives, sealants

